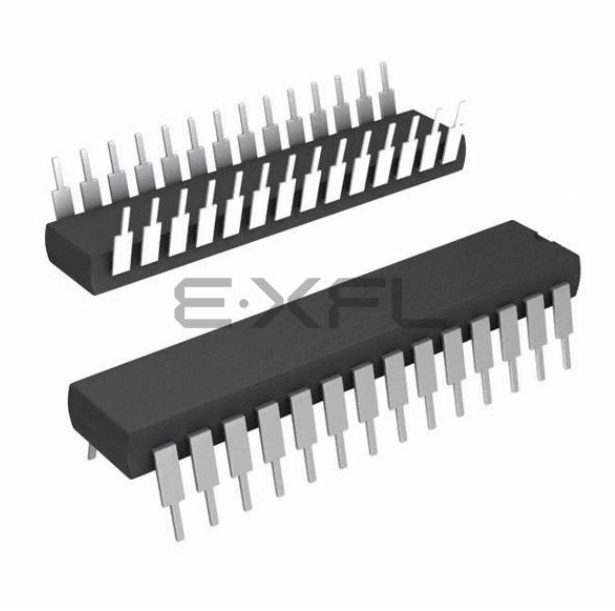
Microchip Technology - DSPIC33EV64GM002-I/SP Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	21
Program Memory Size	64KB (22K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 11x10/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	28-DIP (0.300", 7.62mm)
Supplier Device Package	28-SPDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ev64gm002-i-sp

2.5 ICSP Pins

The PGECx and PGEDx pins are used for ICSP and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not exceeding 100 Ohms.

Pull-up resistors, series diodes and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin Voltage Input High (V_{IH}) and Voltage Input Low (V_{IL}) requirements.

Ensure that the "Communication Channel Select" (i.e., PGECx/PGEDx pins) programmed into the device matches the physical connections for the ICSP to MPLAB® PICkit™ 3, MPLAB ICD 3 or MPLAB REAL ICE™.

For more information on MPLAB ICD 2, ICD 3 and REAL ICE connection requirements, refer to the following documents that are available on the Microchip web site (www.microchip.com).

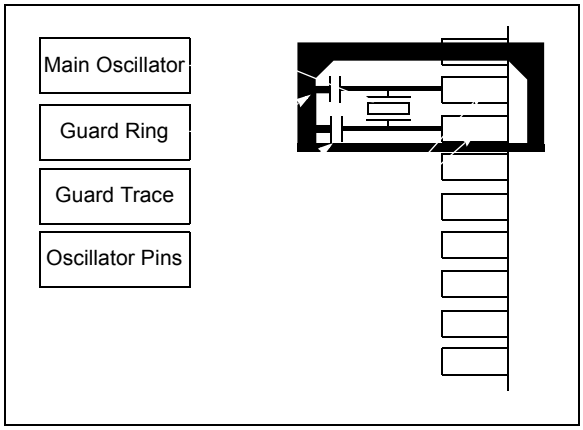
- *"Using MPLAB® ICD 3"* (poster) (DS51765)
- *"MPLAB® ICD 3 Design Advisory"* (DS51764)
- *"MPLAB® REAL ICE™ In-Circuit Emulator User's Guide"* (DS51616)
- *"Using MPLAB® REAL ICE™ In-Circuit Emulator"* (poster) (DS51749)

2.6 External Oscillator Pins

Many DSCs have options for at least two oscillators: a high-frequency primary oscillator and a low-frequency secondary oscillator. For more information, see **Section 9.0 "Oscillator Configuration"**.

The oscillator circuit should be placed on the same side of the board as the device. Also, place the oscillator circuit close to the respective oscillator pins, not exceeding one-half inch (12 mm) distance between them. The load capacitors should be placed next to the oscillator itself, on the same side of the board. Use a grounded copper pour around the oscillator circuit to isolate them from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed as shown in Figure 2-3.

FIGURE 2-3: SUGGESTED PLACEMENT OF THE OSCILLATOR CIRCUIT



2.7 Oscillator Value Conditions on Device Start-up

If the PLL of the target device is enabled and configured for the device start-up oscillator, the maximum oscillator source frequency must be limited to 5 MHz < F_{IN} < 13.6 MHz to comply with device PLL start-up conditions. This intends that, if the external oscillator frequency is outside this range, the application must start up in the FRC mode first. The default PLL settings after a POR with an oscillator frequency outside this range will violate the device operating speed.

Once the device powers up, the application firmware can initialize the PLL SFRs, CLKDIV and PLLFBD, to a suitable value, and then perform a clock switch to the Oscillator + PLL clock source.

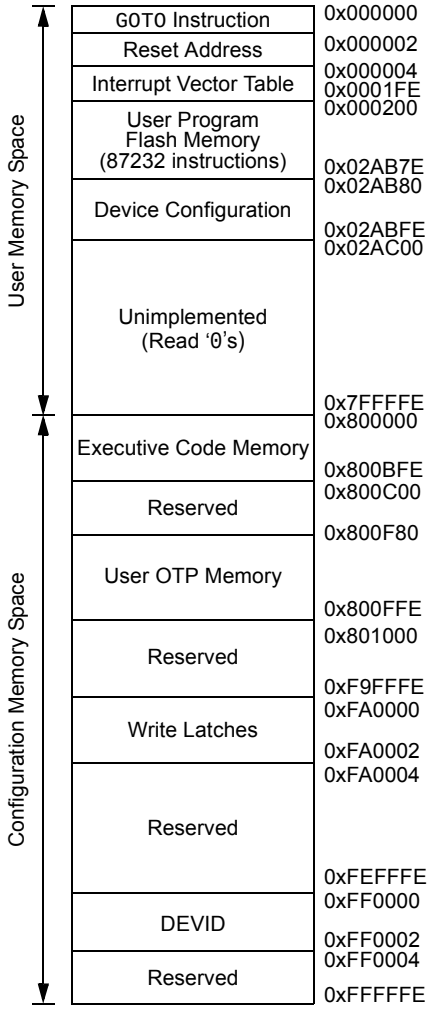
Note:	Clock switching must be enabled in the device Configuration Word.

2.8 Unused I/Os

Unused I/O pins should be configured as outputs and driven to a logic low state.

Alternatively, connect a 1k to 10k resistor between V_{SS} and unused pins, and drive the output to logic low.

FIGURE 4-4: PROGRAM MEMORY MAP FOR dsPIC33EV256GM00X/10X DEVICES(1)



Note 1: Memory areas are not shown to scale.

4.1.1 PROGRAM MEMORY ORGANIZATION

The program memory space is organized in word-addressable blocks. Although it is treated as 24 bits wide, it is more appropriate to think of each address of the program memory as a lower and upper word, with the upper byte of the upper word being unimplemented. The lower word always has an even address, while the upper word has an odd address (see Figure 4-5).

Program memory addresses are always word-aligned on the lower word and addresses are incremented or decremented by two during the code execution. This arrangement provides compatibility with the Data Memory Space Addressing and makes data in the program memory space accessible.

4.1.2 INTERRUPT AND TRAP VECTORS

All dsPIC33EVXXXGM00X/10X family devices reserve the addresses between 0x000000 and 0x000200 for hard-coded program execution vectors. A hardware Reset vector is provided to redirect code execution from the default value of the PC on device Reset to the actual start of code. A GOTO instruction is programmed by the user application at address, 0x000000 of Flash memory, with the actual address for the start of code at address, 0x000002 of Flash memory.

For more information on the Interrupt Vector Tables, see **Section 7.1 “Interrupt Vector Table”**.

FIGURE 4-5: PROGRAM MEMORY ORGANIZATION

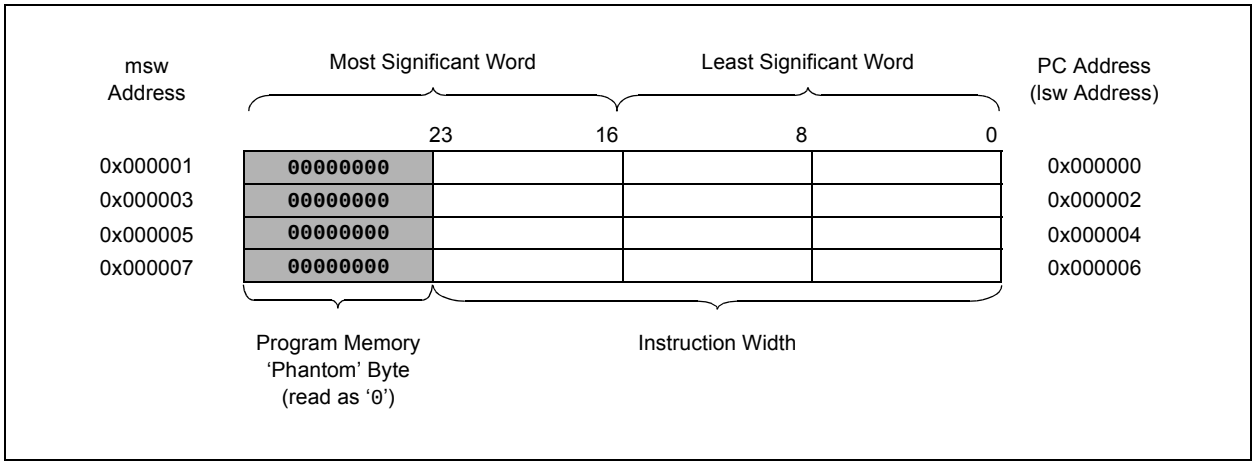


TABLE 4-9: CAN1 REGISTER MAP WHEN WIN (C1CTRL<0>) = 0 OR 1 FOR dsPIC33EVXXXGM10X DEVICES

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
C1CTRL1	0400	—	—	CSIDL	ABAT	CANCKS	REQOP2	REQOP1	REQOP0	OPMODE2	OPMODE1	OPMODE0	—	CANCAP	—	—	WIN	0480
C1CTRL2	0402	—	—	—	—	—	—	—	—	—	—	—	DNCNT<4:0>					0000
C1VEC	0404	—	—	—	FILHIT4	FILHIT3	FILHIT2	FILHIT1	FILHIT0	—	ICODE6	ICODE5	ICODE4	ICODE3	ICODE2	ICODE1	ICODE0	0000
C1FCTRL	0406	DMABS2	DMABS1	DMABS0	—	—	—	—	—	—	—	FSA5	FSA4	FSA3	FSA2	FSA1	FSA0	0000
C1FIFO	0408	—	—	FBP5	FBP4	FBP3	FBP2	FBP1	FBP0	—	—	FNRB5	FNRB4	FNRB3	FNRB2	FNRB1	FNRB0	0000
C1INTF	040A	—	—	TXBO	TXBP	RXBP	TXWAR	RXWAR	EWARN	IVRIF	WAKIF	ERRIF	—	FIFOIF	RBOVIF	RBIF	TBIF	0000
C1INTE	040C	—	—	—	—	—	—	—	—	IVRIE	WAKIE	ERRIE	—	FIFOIE	RBOVIE	RBIE	TBIE	0000
C1EC	040E	TERRCNT7	TERRCNT6	TERRCNT5	TERRCNT4	TERRCNT3	TERRCNT2	TERRCNT1	TERRCNT0	RERRCNT7	RERRCNT6	RERRCNT5	RERRCNT4	RERRCNT3	RERRCNT2	RERRCNT1	RERRCNT0	0000
C1CFG1	0410	—	—	—	—	—	—	—	—	SJW1	SJW0	BRP5	BRP4	BRP3	BRP2	BRP1	BRP0	0000
C1CFG2	0412	—	WAKFIL	—	—	—	SEG2PH2	SEG2PH1	SEG2PH0	SEG2PHTS	SAM	SEG1PH2	SEG1PH1	SEG1PH0	PRSEG2	PRSEG1	PRSEG0	0000
C1FEN1	0414	FLTEN<15:0>																FFFF
C1FMSKSEL1	0418	F7MSK1	F7MSK0	F6MSK1	F6MSK0	F5MSK1	F5MSK0	F4MSK1	F4MSK0	F3MSK1	F3MSK0	F2MSK1	F2MSK0	F1MSK1	F1MSK0	F0MSK1	F0MSK0	0000
C1FMSKSEL2	041A	F15MSK1	F15MSK0	F14MSK1	F14MSK0	F13MSK1	F13MSK0	F12MSK1	F12MSK0	F11MSK1	F11MSK0	F10MSK1	F10MSK0	F9MSK1	F9MSK0	F8MSK1	F8MSK0	0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-10: CAN1 REGISTER MAP WHEN WIN (C1CTRL<0>) = 0 FOR dsPIC33EVXXXGM10X DEVICES

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
	0400-041E	See definition when WIN = x																
C1RXFUL1	0420	RXFUL<15:0>																0000
C1RXFUL2	0422	RXFUL<31:16>																0000
C1RXOVF1	0428	RXOVF<15:0>																0000
C1RXOVF2	042A	RXOVF<31:16>																0000
C1TR01CON	0430	TXEN1	TXABT1	TXLARB1	TXERR1	TXREQ1	RTREN1	TX1PRI1	TX1PRI0	TXEN0	TXABAT0	TXLARB0	TXERR0	TXREQ0	RTREN0	TX0PRI1	TX0PRI0	0000
C1TR23CON	0432	TXEN3	TXABT3	TXLARB3	TXERR3	TXREQ3	RTREN3	TX3PRI1	TX3PRI0	TXEN2	TXABAT2	TXLARB2	TXERR2	TXREQ2	RTREN2	TX2PRI1	TX2PRI0	0000
C1TR45CON	0434	TXEN5	TXABT5	TXLARB5	TXERR5	TXREQ5	RTREN5	TX5PRI1	TX5PRI0	TXEN4	TXABAT4	TXLARB4	TXERR4	TXREQ4	RTREN4	TX4PRI1	TX4PRI0	0000
C1TR67CON	0436	TXEN7	TXABT7	TXLARB7	TXERR7	TXREQ7	RTREN7	TX7PRI1	TX7PRI0	TXEN6	TXABAT6	TXLARB6	TXERR6	TXREQ6	RTREN6	TX6PRI1	TX6PRI0	xxxx
C1RXD	0440	CAN1 Receive Data Word Register																xxxx
C1TXD	0442	CAN1 Transmit Data Word Register																xxxx

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

4.5 Modulo Addressing

Modulo Addressing mode is a method of providing an automated means to support circular data buffers using hardware. The objective is to remove the need for software to perform data address boundary checks when executing tightly looped code, as is typical in many DSP algorithms.

Modulo Addressing can operate in either Data or Program Space (since the Data Pointer mechanism is essentially the same for both). One circular buffer can be supported in each of the X (which also provides the pointers into Program Space) and Y Data Spaces. Modulo Addressing can operate on any W Register Pointer. However, it is not advisable to use W14 or W15 for Modulo Addressing, since these two registers are used as the SFP and SSP, respectively.

In general, any particular circular buffer can be configured to operate in only one direction, as there are certain restrictions on the buffer start address (for incrementing buffers) or end address (for decrementing buffers), based upon the direction of the buffer.

The only exception to the usage restrictions is for buffers that have a power-of-two length. As these buffers satisfy the start and end address criteria, they can operate in a Bidirectional mode (that is, address boundary checks are performed on both the lower and upper address boundaries).

4.5.1 START AND END ADDRESS

The Modulo Addressing scheme requires that a starting and ending address be specified and loaded into the 16-bit Modulo Buffer Address registers: XMODSRT, XMODEND, YMODSRT and YMODEND (see Table 4-1).

Note:	Y Data Space Modulo Addressing EA calculations assume word-sized data (LSb of every EA is always clear).

The length of a circular buffer is not directly specified. It is determined by the difference between the corresponding start and end addresses. The maximum possible length of the circular buffer is 32K words (64 Kbytes).

4.5.2 W ADDRESS REGISTER SELECTION

The Modulo and Bit-Reversed Addressing Control register, MODCON<15:0>, contains enable flags, as well as a W register field to specify the W Address registers. The XWM and YWM fields select the registers that operate with Modulo Addressing:

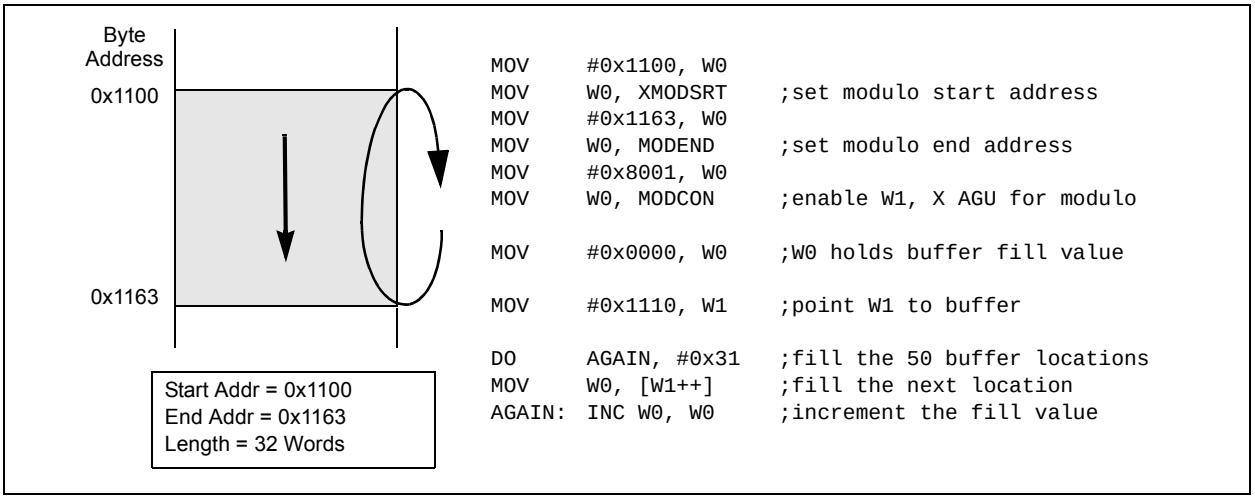
- If XWM = 1111, X RAGU and X WAGU Modulo Addressing is disabled
- If YWM = 1111, Y AGU Modulo Addressing is disabled

The X Address Space Pointer W register (XWM) to which Modulo Addressing is to be applied is stored in MODCON<3:0> (see Table 4-1). Modulo Addressing is enabled for X Data Space when XWM is set to any value other than '1111' and the XMODEN bit (MODCON<15>) is set

The Y Address Space Pointer W register (YWM) to which Modulo Addressing is to be applied is stored in MODCON<7:4>. Modulo Addressing is enabled for Y Data Space when YWM is set to any value other than '1111' and the YMODEN bit (MODCON<14>) is set.

Figure 4-15 shows an example of Modulo Addressing operation.

FIGURE 4-15: MODULO ADDRESSING OPERATION EXAMPLE



REGISTER 8-5: DMAxSTBH: DMA CHANNEL x START ADDRESS REGISTER B (HIGH)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
STB<23:16>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as ‘0’

bit 7-0 **STB<23:16>:** DMA Secondary Start Address bits (source or destination)

REGISTER 8-6: DMAxSTBL: DMA CHANNEL x START ADDRESS REGISTER B (LOW)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
STB<15:8>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
STB<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **STB<15:0>:** DMA Secondary Start Address bits (source or destination)

REGISTER 8-14: DMAPPS: DMA PING-PONG STATUS REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	R-0	R-0	R-0	R-0
—	—	—	—	PPST3	PPST2	PPST1	PPST0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-4 **Unimplemented:** Read as ‘0’

bit 3 **PPST3:** Channel 3 Ping-Pong Mode Status Flag bit
1 = DMA3STB register is selected
0 = DMA3STA register is selected

bit 2 **PPST2:** Channel 2 Ping-Pong Mode Status Flag bit
1 = DMA2STB register is selected
0 = DMA2STA register is selected

bit 1 **PPST1:** Channel 1 Ping-Pong Mode Status Flag bit
1 = DMA1STB register is selected
0 = DMA1STA register is selected

bit 0 **PPST0:** Channel 0 Ping-Pong mode Status Flag bit
1 = DMA0STB register is selected
0 = DMA0STA register is selected

REGISTER 15-2: ICxCON2: INPUT CAPTURE x CONTROL REGISTER 2 (CONTINUED)

bit 4-0 **SYNCSEL<4:0>:** Input Source Select for Synchronization and Trigger Operation bits(4)

11111 = Reserved
11110 = Reserved
11101 = Reserved
11100 = CTMU trigger is the source for the capture timer synchronization
11011 = ADC1 interrupt is the source for the capture timer synchronization(5)
11010 = Analog Comparator 3 is the source for the capture timer synchronization(5)
11001 = Analog Comparator 2 is the source for the capture timer synchronization(5)
11000 = Analog Comparator 1 is the source for the capture timer synchronization(5)
10111 = Analog Comparator 5 is the source for the capture timer synchronization(5)
10110 = Analog Comparator 4 is the source for the capture timer synchronization(5)
10101 = Reserved
10100 = Reserved
10011 = Input Capture 4 interrupt is the source for the capture timer synchronization
10010 = Input Capture 3 interrupt is the source for the capture timer synchronization
10001 = Input Capture 2 interrupt is the source for the capture timer synchronization
10000 = Input Capture 1 interrupt is the source for the capture timer synchronization
01111 = GP Timer5 is the source for the capture timer synchronization
01110 = GP Timer4 is the source for the capture timer synchronization
01101 = GP Timer3 is the source for the capture timer synchronization
01100 = GP Timer2 is the source for the capture timer synchronization
01011 = GP Timer1 is the source for the capture timer synchronization
01010 = Reserved
01001 = Reserved
01000 = Input Capture 4 is the source for the capture timer synchronization(6)
00111 = Input Capture 3 is the source for the capture timer synchronization(6)
00110 = Input Capture 2 is the source for the capture timer synchronization(6)
00101 = Input Capture 1 is the source for the capture timer synchronization(6)
00100 = Output Compare 4 is the source for the capture timer synchronization
00011 = Output Compare 3 is the source for the capture timer synchronization
00010 = Output Compare 2 is the source for the capture timer synchronization
00001 = Output Compare 1 is the source for the capture timer synchronization
00000 = Reserved

Note 1: The IC32 bit in both the odd and even ICx must be set to enable Cascade mode.
2: The input source is selected by the SYNCSEL<4:0> bits of the ICxCON2 register.
3: This bit is set by the selected input source (selected by the SYNCSEL<4:0> bits); it can be read, set and cleared in software.
4: Do not use the ICx module as its own sync or trigger source.
5: This option should only be selected as a trigger source and not as a synchronization source.
6: When the source ICx timer rolls over, then in the next clock cycle, trigger or synchronization occurs.

16.0 OUTPUT COMPARE

Note 1: This data sheet summarizes the features of the dsPIC33EVXXXGM00X/10X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Output Compare"** (DS70005157) in the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

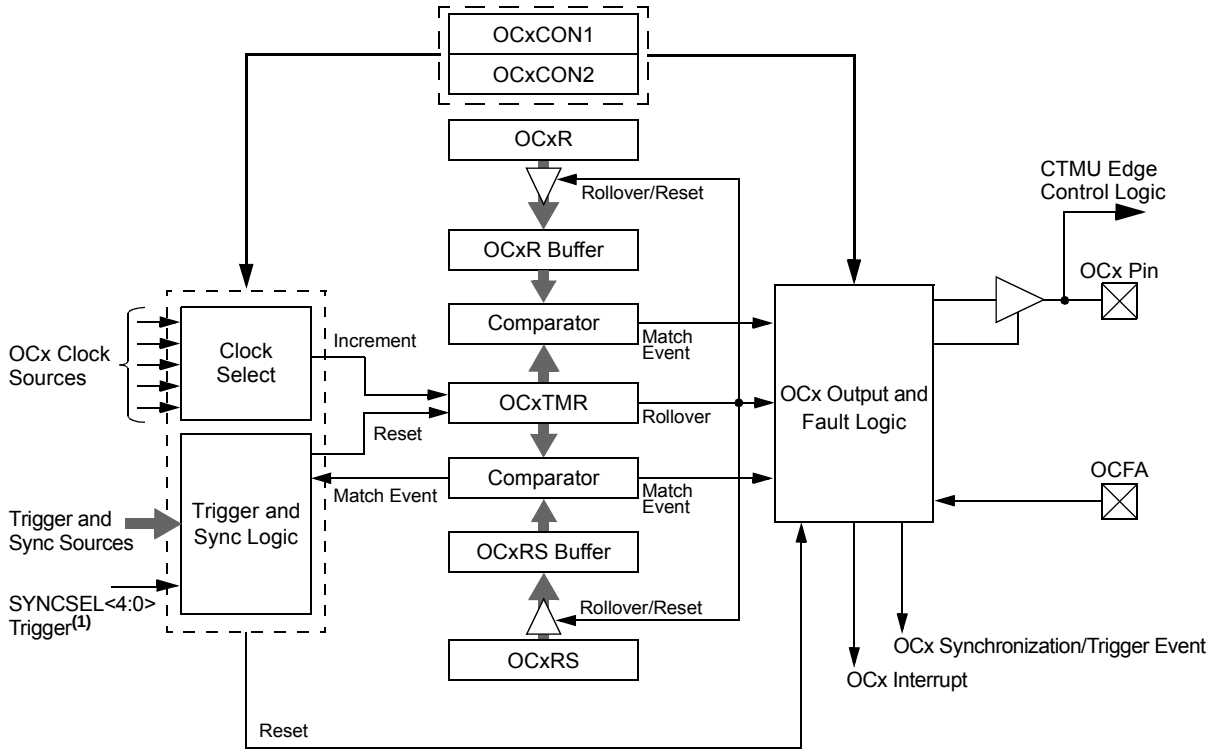
2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33EVXXXGM00X/10X family devices support up to 4 output compare modules. The output compare module can select one of eight available clock sources for its time base. The module compares the value of the timer with the value of one or two Compare registers, depending on the operating mode selected. The state of the output pin changes when the timer value matches the Compare register value. The output compare module generates either a single output pulse, or a sequence of output pulses, by changing the state of the output pin on the compare match events. The output compare module can also generate interrupts on compare match events and trigger DMA data transfers.

Figure 16-1 shows a block diagram of the output compare module.

Note: For more information on OCxR and OCxRS register restrictions, refer to the **"Output Compare"** (DS70005157) section in the *"dsPIC33/PIC24 Family Reference Manual"*.

FIGURE 16-1: OUTPUT COMPARE x MODULE BLOCK DIAGRAM



Note 1: The trigger/sync source is enabled by default and is set to Timer2 as a source. This timer must be enabled for proper OCx module operation or the trigger/sync source must be changed to another source option.

REGISTER 20-1: SENTxCON1: SENTx CONTROL REGISTER 1

R/W-0	U-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
SNTEN	—	SNTSIDL	—	RCVEN	TXM(1)	TXPOL(1)	CRCEN
bit 15							bit 8

R/W-0	R/W-0	U-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0
PPP	SPCEN(2)	—	PS	—	NIBCNT2	NIBCNT1	NIBCNT0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **SNTEN:** SENTx Enable bit
1 = SENTx is enabled
0 = SENTx is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **SNTSIDL:** SENTx Stop in Idle Mode bit
1 = Discontinues module operation when the device enters Idle mode
0 = Continues module operation in Idle mode

bit 12 **Unimplemented:** Read as '0'

bit 11 **RCVEN:** SENTx Receive Enable bit
1 = SENTx operates as a receiver
0 = SENTx operates as a transmitter (sensor)

bit 10 **TXM:** SENTx Transmit Mode bit(1)
1 = SENTx transmits data frame only when triggered using the SYNCTXEN status bit
0 = SENTx transmits data frames continuously while SNTEN = 1

bit 9 **TXPOL:** SENTx Transmit Polarity bit(1)
1 = SENTx data output pin is low in the Idle state
0 = SENTx data output pin is high in the Idle state

bit 8 **CRCEN:** CRC Enable bit
Module in Receive Mode (RCVEN = 1):
1 = SENTx performs CRC verification on received data using the preferred J2716 method
0 = SENTx does not perform CRC verification on received data
Module in Transmit Mode (RCVEN = 1):
1 = SENTx automatically calculates CRC using the preferred J2716 method
0 = SENTx does not calculate CRC

bit 7 **PPP:** Pause Pulse Present bit
1 = SENTx is configured to transmit/receive SENT messages with pause pulse
0 = SENTx is configured to transmit/receive SENT messages without pause pulse

bit 6 **SPCEN:** Short PWM Code Enable bit(2)
1 = SPC control from external source is enabled
0 = SPC control from external source is disabled

bit 5 **Unimplemented:** Read as '0'

bit 4 **PS:** SENTx Module Clock Prescaler (divider) bits
1 = Divide-by-4
0 = Divide-by-1

Note 1: This bit has no function in Receive mode (RCVEN = 1).
2: This bit has no function in Transmit mode (RCVEN = 0).

REGISTER 24-7: ADxCSSH: ADCx INPUT SCAN SELECT REGISTER HIGH(2)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CSS31	CSS30	CSS29	CSS28	CSS27	CSS26(1)	CSS25(1)	CSS24(1)
bit 15							bit 8

U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	—	CSS19	CSS18	CSS17	CSS16
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **CSS31:** ADCx Input Scan Selection bit
1 = Selects ANx for input scan
0 = Skips ANx for input scan

bit 14 **CSS30:** ADCx Input Scan Selection bit
1 = Selects ANx for input scan
0 = Skips ANx for input scan

bit 13 **CSS29:** ADCx Input Scan Selection bits
1 = Selects ANx for input scan
0 = Skips ANx for input scan

bit 12 **CSS28:** ADCx Input Scan Selection bit
1 = Selects ANx for input scan
0 = Skips ANx for input scan

bit 11 **CSS27:** ADCx Input Scan Selection bit
1 = Selects ANx for input scan
0 = Skips ANx for input scan

bit 10 **CSS26:** ADCx Input Scan Selection bit(1)
1 = Selects OA3/AN6 for input scan
0 = Skips OA3/AN6 for input scan

bit 9 **CSS25:** ADCx Input Scan Selection bit(1)
1 = Selects OA2/AN0 for input scan
0 = Skips OA2/AN0 for input scan

bit 8 **CSS24:** ADCx Input Scan Selection bit(1)
1 = Selects OA1/AN3 for input scan
0 = Skips OA1/AN3 for input scan

bit 7-4 **Unimplemented:** Read as '0'

bit 3 **CSS19:** ADCx Input Scan Selection bit
1 = Selects ANx for input scan
0 = Skips ANx for input scan

bit 2 **CSS18:** ADCx Input Scan Selection bit
1 = Selects ANx for input scan
0 = Skips ANx for input scan

Note 1: If the op amp is selected (OPAEN bit (CMxCON<10>) = 1), the OAx input is used; otherwise, the ANx input is used.

2: All bits in this register can be selected by the user application. However, inputs selected for scan without a corresponding input on the device convert VREFL.

29.11 Demonstration/Development Boards, Evaluation Kits, and Starter Kits

A wide variety of demonstration, development and evaluation boards for various PIC MCUs and dsPIC DSCs allows quick application development on fully functional systems. Most boards include prototyping areas for adding custom circuitry and provide application firmware and source code for examination and modification.

The boards support a variety of features, including LEDs, temperature sensors, switches, speakers, RS-232 interfaces, LCD displays, potentiometers and additional EEPROM memory.

The demonstration and development boards can be used in teaching environments, for prototyping custom circuits and for learning about various microcontroller applications.

In addition to the PICDEM™ and dsPICDEM™ demonstration/development board series of circuits, Microchip has a line of evaluation kits and demonstration software for analog filter design, KEELOQ® security ICs, CAN, IrDA®, PowerSmart battery management, SEEVAL® evaluation system, Sigma-Delta ADC, flow rate sensing, plus many more.

Also available are starter kits that contain everything needed to experience the specified device. This usually includes a single application and debug capability, all on one board.

Check the Microchip web page (www.microchip.com) for the complete list of demonstration, development and evaluation kits.

29.12 Third-Party Development Tools

Microchip also offers a great collection of tools from third-party vendors. These tools are carefully selected to offer good value and unique functionality.

- Device Programmers and Gang Programmers from companies, such as SoftLog and CCS
- Software Tools from companies, such as Gimpel and Trace Systems
- Protocol Analyzers from companies, such as Saleae and Total Phase
- Demonstration Boards from companies, such as MikroElektronika, Digilent® and Olimex
- Embedded Ethernet Solutions from companies, such as EZ Web Lynx, WIZnet and IPLogika®

TABLE 30-22: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SY00	TPU	Power-up Period	—	400	600	µs	
SY10	TOST	Oscillator Start-up Time	—	1024 TOSC	—	—	TOSC = OSC1 period
SY11	TPWRT	Power-up Timer Period	—	1	—	ms	Using LPRC parameters indicated in F21a/F21b (see Table 30-20)
SY12	TWDT	Watchdog Timer Time-out Period	0.8	—	1.2	ms	WDTPRE = 0, WDTPS<3:0> = 0000, using LPRC tolerances indicated in F21a/F21b (see Table 30-20) at +85°C
			3.2	—	4.8	ms	WDTPRE = 1, WDTPS<3:0> = 0000, using LPRC tolerances indicated in F21a/F21b (see Table 30-20) at +85°C
SY13	TIOZ	I/O High-Impedance from MCLR Low or Watchdog Timer Reset	0.68	0.72	1.2	µs	
SY20	TMCLR	MCLR Pulse Width (low)	2	—	—	µs	
SY30	TBOR	BOR Pulse Width (low)	1	—	—	ms	
SY35	TFSCM	Fail-Safe Clock Monitor Delay	—	500	900	µs	-40°C to +85°C
SY36	TVREG	Voltage Regulator Standby-to-Active mode Transition Time	—	—	30	µs	
SY37	TOSCDFRC	FRC Oscillator Start-up Delay	46	48	54	µs	
SY38	TOSCDLPRC	LPRC Oscillator Start-up Delay	—	—	70	µs	

Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in "Typ." column is at 5.0V, +25°C unless otherwise stated.

FIGURE 30-16: SPI2 SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 0, SMP = 0) TIMING CHARACTERISTICS

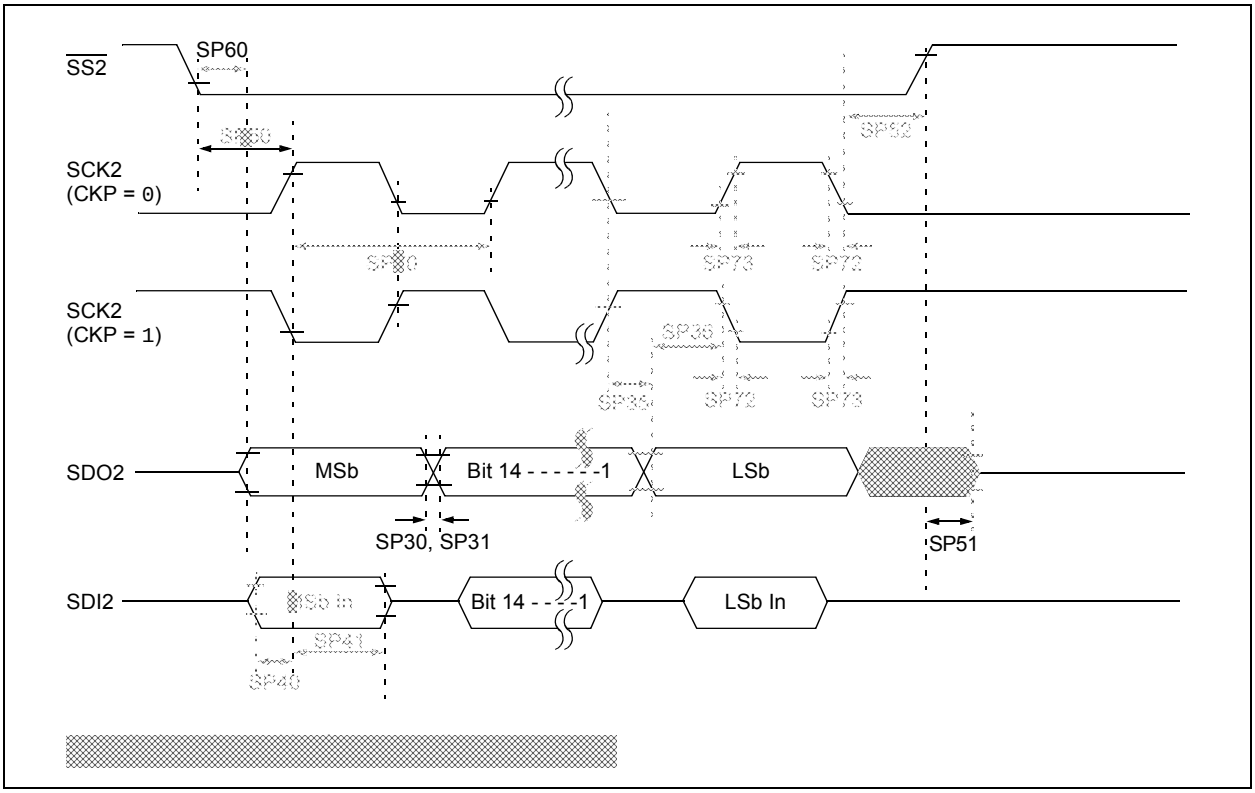
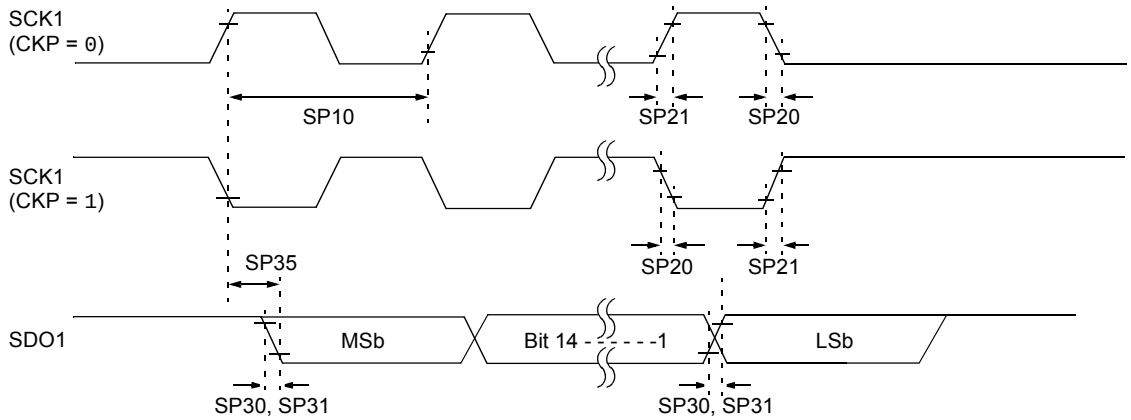


TABLE 30-38: SPI1 MAXIMUM DATA/CLOCK RATE SUMMARY

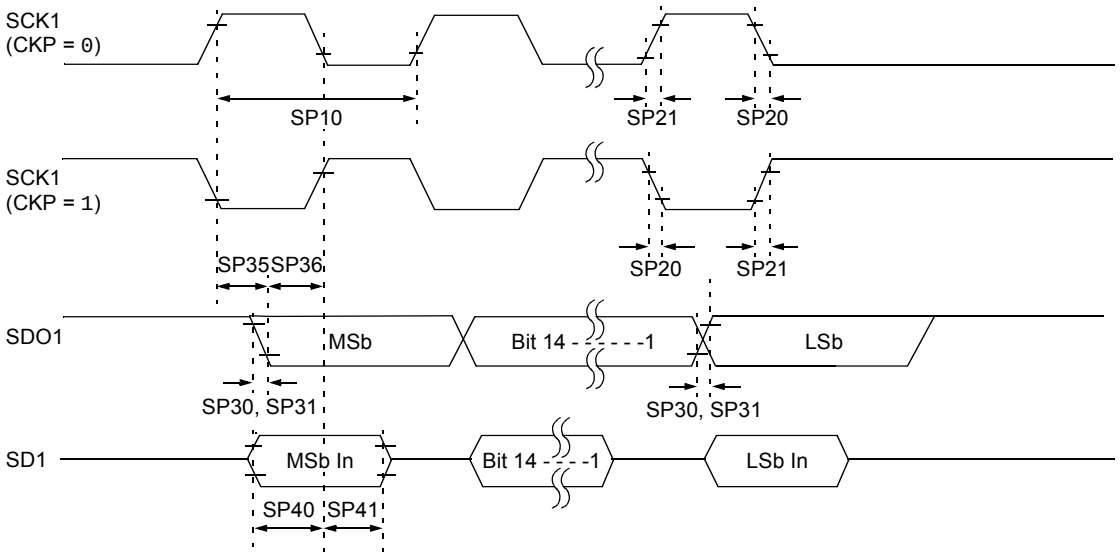
AC CHARACTERISTICS			Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Maximum Data Rate	**Master Transmit Only (Half-Duplex)**	**Master Transmit/Receive (Full-Duplex)**	**Slave Transmit/Receive (Full-Duplex)**	**CKE**	**CKP**	**SMP**
25 MHz	Table 30-39	—	—	0,1	0,1	0,1
25 MHz	—	Table 30-40	—	1	0,1	1
25 MHz	—	Table 30-41	—	0	0,1	1
25 MHz	—	—	Table 30-42	1	0	0
25 MHz	—	—	Table 30-43	1	1	0
25 MHz	—	—	Table 30-44	0	1	0
25 MHz	—	—	Table 30-45	0	0	0

FIGURE 30-20: SPI1 MASTER MODE (HALF-DUPLEX, TRANSMIT ONLY, CKE = 0) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

FIGURE 30-23: SPI1 MASTER MODE (FULL-DUPLEX, CKE = 0, CKP = x, SMP = 1) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

FIGURE 33-11: TYPICAL IDOZE VS. VDD (DOZE 1:128, 70 MIPS)

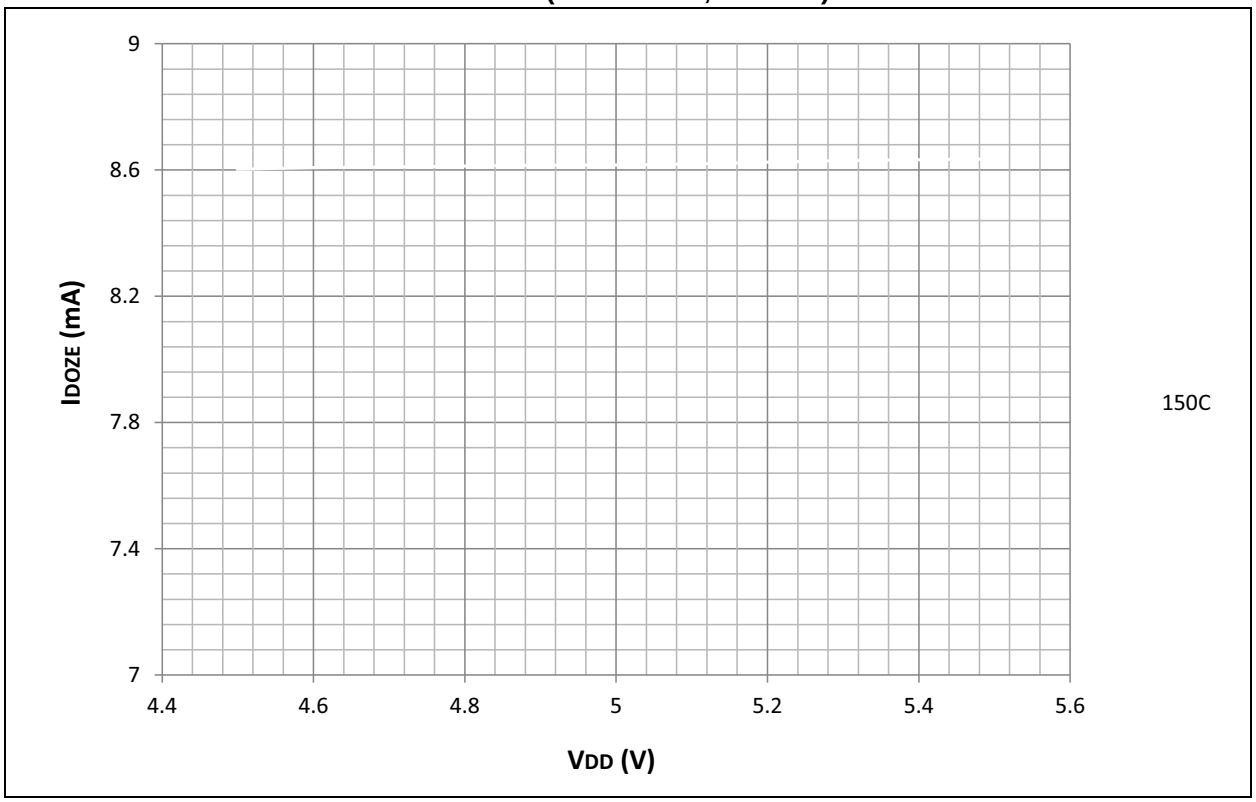
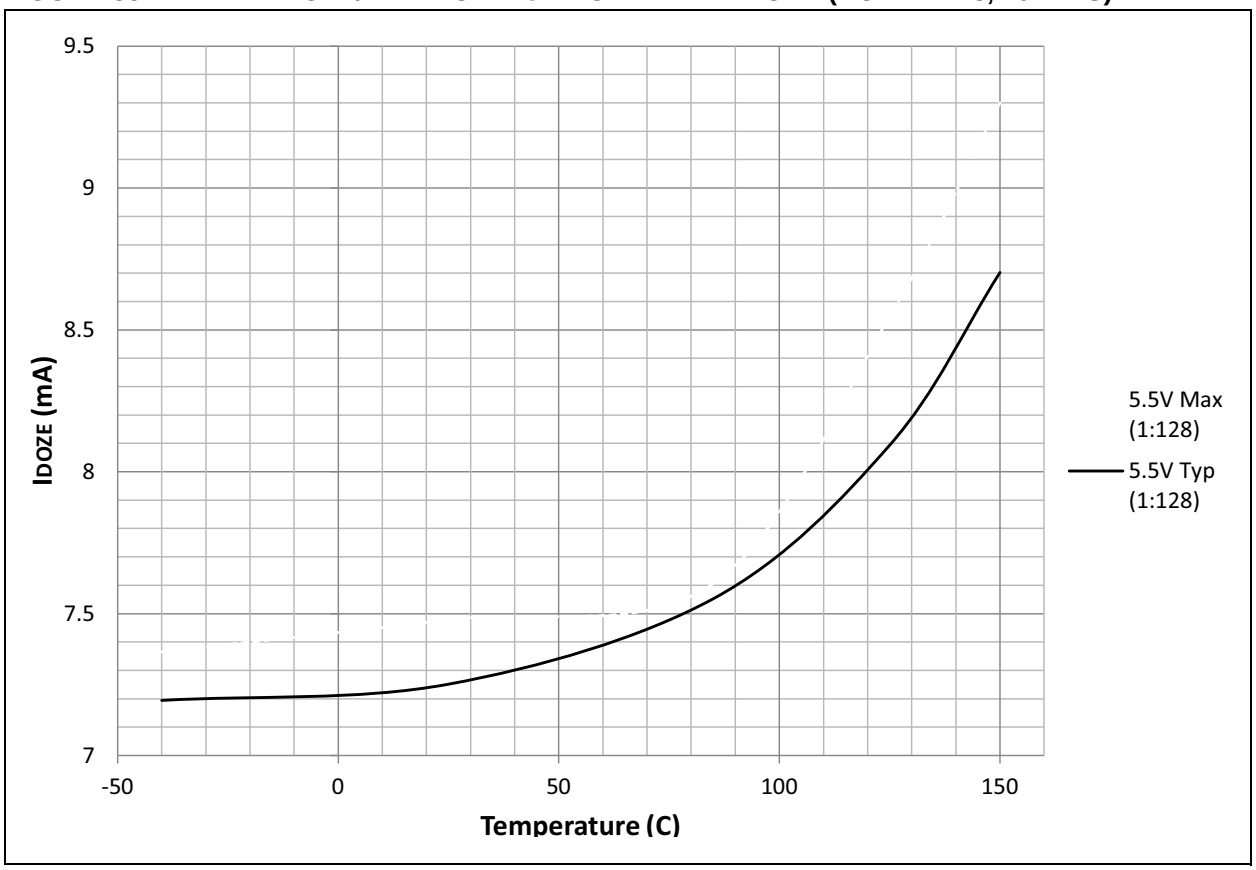
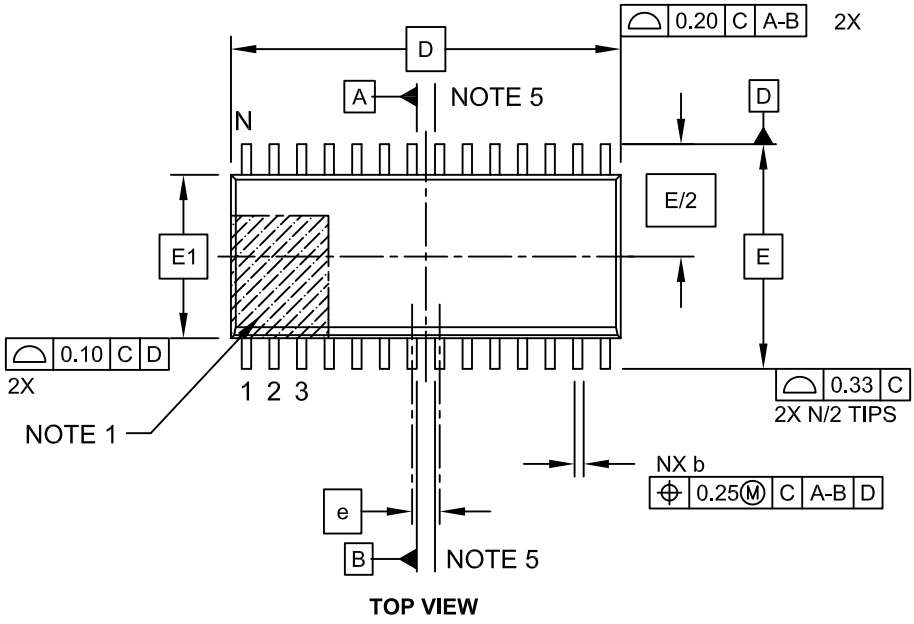


FIGURE 33-12: TYPICAL/MAXIMUM IDOZE VS. TEMPERATURE (DOZE 1:128, 70 MIPS)

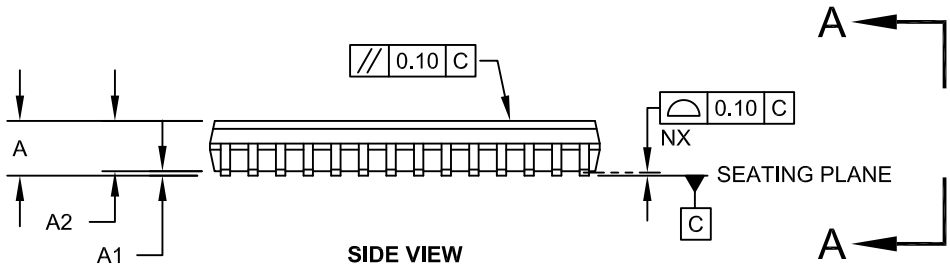


28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

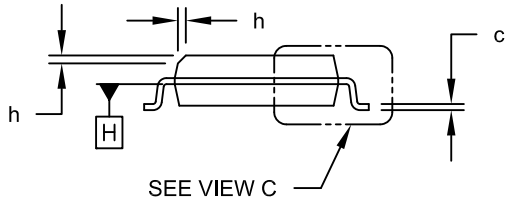
Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



TOP VIEW



SIDE VIEW

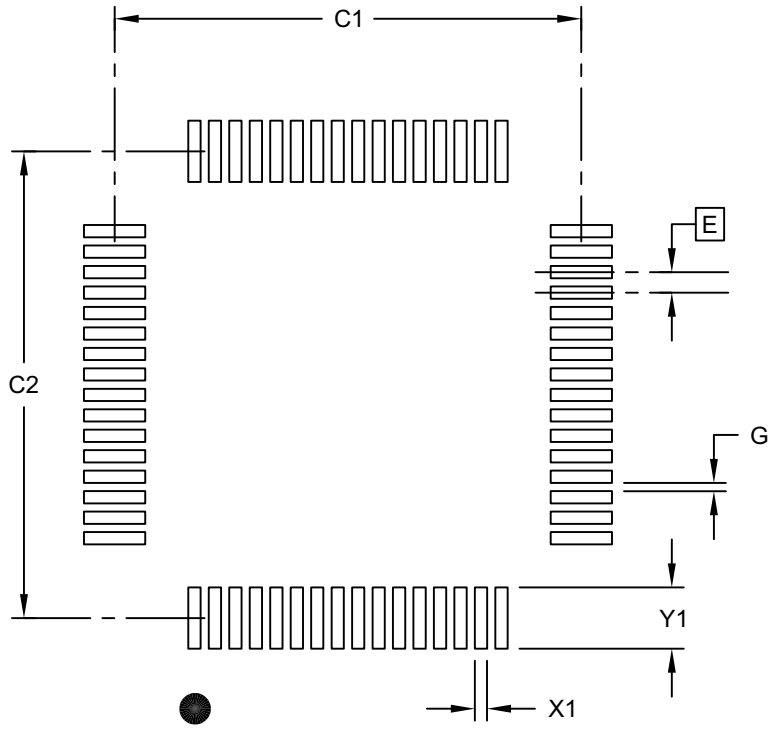


VIEW A-A

Microchip Technology Drawing C04-052C Sheet 1 of 2

64-Lead Plastic Thin Quad Flatpack (PT)-10x10x1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.50 BSC	
Contact Pad Spacing	C1		11.40	
Contact Pad Spacing	C2		11.40	
Contact Pad Width (X28)	X1			0.30
Contact Pad Length (X28)	Y1			1.50
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-2085B Sheet 1 of 1

Revision E (September 2016)

This revision incorporates the following updates:

- Sections:
  - Added new **Section 32.0 “Characteristics for Industrial/Extended Temperature Devices (-40°C to +125°C)”** and **Section 33.0 “Characteristics for High-Temperature Devices (+150°C)”**.
  - Updated the **Qualification and Class B Support** section.
  - Updated **Section 27.6 “In-Circuit Serial Programming”**.
  - Updated **Section 34.0 “Packaging Information”** with the addition of the 28-Lead SSOP package information and new packaging diagram revisions.
  - Updated the **“Product Identification System”** section with the addition of the 28-Lead SSOP package.
- Figures:
  - Updated Figure 4-6.
- Registers:
  - Updated Register 25-2, Register 25-3, Register 27-1 and Register 27-2.
- Tables:
  - Updated Table 30-7, Table 30-9, Table 30-39, Table 30-40, Table 30-41, Table 30-42, Table 30-43, Table 30-44 and Table 30-45.